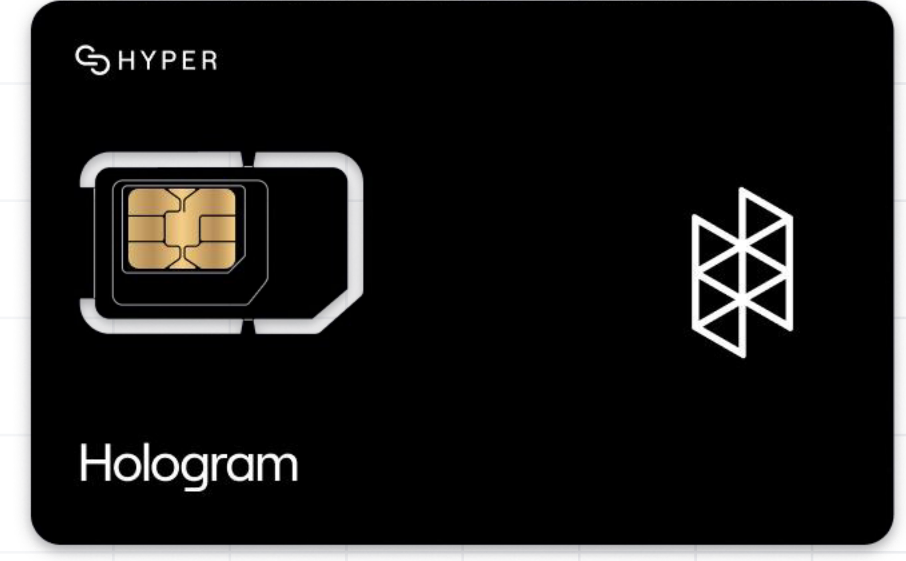
Hologram

Triple cut format



Hyper eUICC SIM

Hyper eUICC SIM - Triple cut format

Product overview

A secure, device-agnostic IoT SIM card for global deployments built for M2M data, with easy activation, transparent pricing, and developer-friendly tools. Hologram's Hyper SIM platform is eUICC compliant and remotely updates coverage over-the-air by adding or removing connectivity profiles, without requiring you to swap the SIM in your device. Network fallback functionality can dynamically switch profiles in the event that a profile loses connectivity.

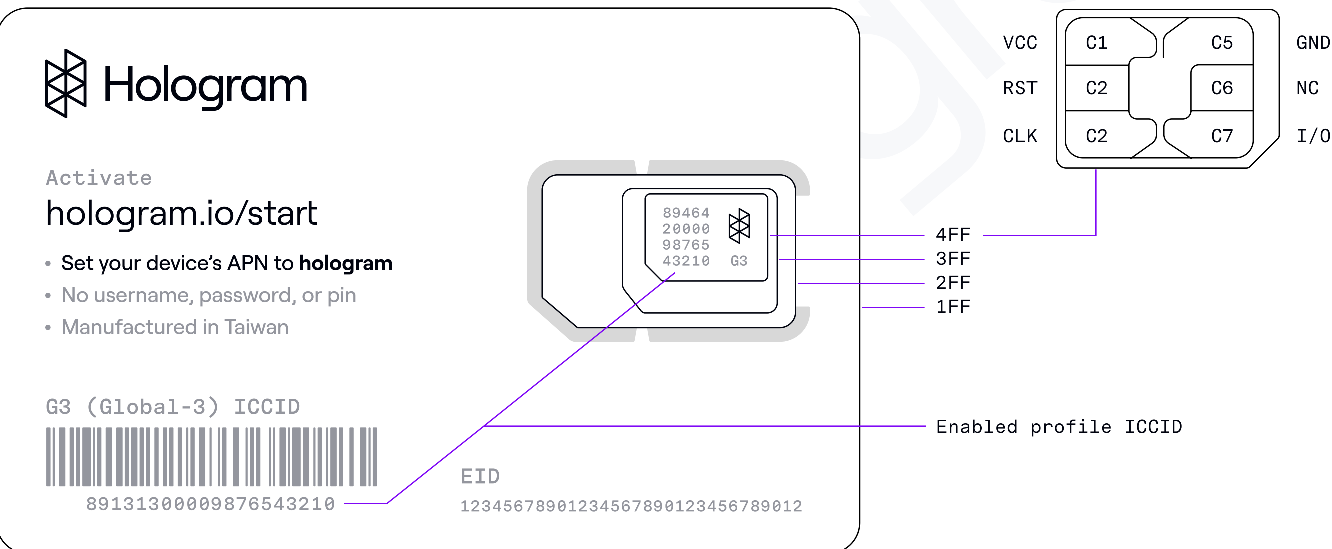
Primary part number

G3

Network availability

Works globally with Hologram's 2G through 5G network including LTE-M and NB-IoT where coverage is available. More information: https://www.hologram.io/pricing/coverage

Card layout



Physical characteristics

Size

1FF	Full-size	85.6 x 54 x 0.71 mm
2FF	Mini-SIM	25 x 15 x 0.71 mm
3FF	Micro-SIM	15 x 12 x 0.71 mm
4FF	Nano-SIM	12.3 x 8.8 x 0.71 mm

Pin definitions

C1	VCC	Input Voltage
C2	RST	Reset
C3	CLK	Clock
C5	GND	Ground
C6	NC	No Connect
C7	I/O	Input/Output

Hardware features

Chip type

Supplier	Infineon
Chip Code	SLM17ECB800B

Electrical

Operating Voltage	1.62V to 5.5V

Hardware characteristics

Grade	Industrial
Operational Temperature	−40°C to +105°C
Data Retention	10 years @ 25°C
Write Endurance	>1.5M cycles
Memory (NVM)	800 KB
Memory (SRAM)	20 KB

AC electrical parameters standards

ETSI 3GPP TS 102 221 v16.0.0 - Smart Cards; UICC-Terminal interface; Physical and logical characteristics
ISO/IEC 7816, T=0 standard for Cards with contacts — USB electrical interface and operating procedures

Compliance

Chip	Common Criteria	EAL 4+ PP-0084 (chipset) Certificate: BSI-DSZ-CC-1126-V2-2021
OS	GSMA	SGP.01 Embedded SIM Remote Provisioning Architecture v4.2 SGP.02 Embedded UICC Technical Specification v4.2 SGP.16 M2M Compliance Process v1.3
	TCA Trusted Connectivity Alliance	SIMalliance eUICC Profile Package Interoperable Format Technical Specification v2.3.1
	GlobalPlatform	Card Specification Version 2.3.1 Card Specification Amendments A, B, D & E
Software	ORACLE Java Card	Java Card 3 Platform, Classic Edition version 3.0.5
	3GPP A Global Initiative	Release 16
Remote SIM provisioning	GSMA	SGP.01 Embedded SIM Remote Provisioning Architecture v4.2 SGP.02 Embedded UICC Technical Specification v4.2 SGP.16 M2M Compliance Process v1.3
Supplier's Declaration of Conformity		Manufactured according to the following standards: • RoHS 2015/863/EU • Reach certification • GSMA SAS-UP • ISO 9001:2015 • ISO 27001 • ISO 14001

Part numbers

Active part numbers	Past part numbers
G3	G3-F
G3-G2-F	—
G1-G2-F	—
G2-F	GL2-AFB
G1-F	—
US2+-G2-F	GL2-AFB-USA2+
US2M-G2-F	GL2-AFB-USAM
CA1-G2-F	GL2-AFB-CA1

Multipack labeling

Single SIM: G3-G2-F
10-pack: G3-G2-F-10
100-pack: G3-G2-F-100
1000-pack: G3-G2-F-1000

Multi-core card layout